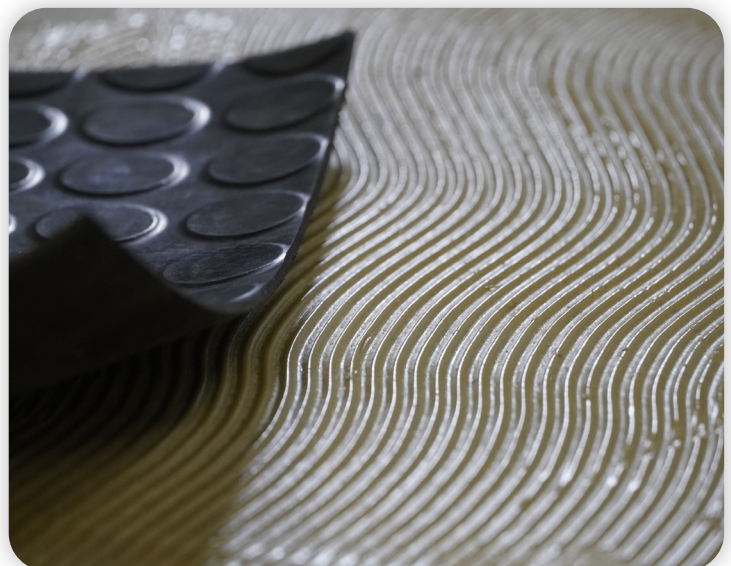
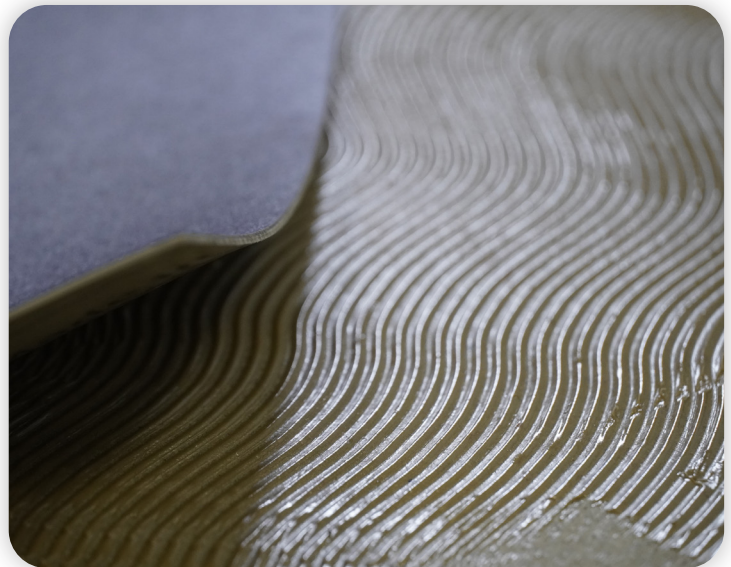







Lechner

SOLUTIONS FOR PROFESSIONAL CONSTRUCTION



FIELDS OF APPLICATION

-  RESILIENT LINE
-  WOOD LINE
-  MARINE LINE
-  ARTIFICIAL GRASS LINE
-  EQUIPMENT AND ACCESSORIES LINE

HYCOL KD4 CONDUTTIVO

ACRYLIC ADHESIVE SUITABLE FOR THE INSTALLATION OF CONDUCTIVE AND STATIC FLOORS - DISSIPATIVE IN PVC, RUBBER AND TEXTILE

DESCRIPTION AND USES PRODUCT FOR PROFESSIONAL USE ONLY

Conductive acrylic adhesive in water dispersion with special fibres, suitable for laying conductive or statically dissipative PVC, rubber and textile floors on absorbent substrates.

PRODUCT FEATURES



Application

Lechner toothed trowel no.1- no.2



Suitable for conductive flooring



Suitable for indoor use



Suitable for under-floor heating systems



Suitable for wheelchairs

Waiting time

10 mins

Open time

40 minutes

Dry-to-walk-on time

4 hours

Final setting time

48-72 hours



Appearance

Paste



Color

Grey



Chemical base

Acrylic resin in aqueous dispersion and conductive pigments and special fibers



Storage

12 months in original sealed packaging



Consumption

300-400 g/m²



Operating temperature

+10 - +30 °C



Cleaning

Water (as long as the product is fresh)



Solvent-free product

Adhesive suitable for installation of resilient ESD<1.0 x 10⁹ OHM and higher than its electrical resistance value according to IEC 61340-5-1

METHOD OF USE

The substrate must be flat, absorbent, compact, in good condition, clean, established, uniformly dry and free from detaching substances such as oils, waxes, excess dust, etc. If there are any cracks or fissures, these must be first repaired with SIGEPOX. Maximum allowable residual moisture content:

- Cementitious substrates: max. 2.0%; with underfloor heating max. 1.7%
- Gypsum or anhydrite substrates: max. 0.5%; with underfloor heating max. 0.2%.

For higher R.H. values, please contact the Lechner S.p.A. Technical Service Department.

It is recommended to check that there is no rising damp, in which case it is not possible to install.

If surfaces are dusty, insufficiently compact or highly absorbent, they should be treated in advance with the appropriate primers: PRIMER 99 or PRIMER AC PLUS. An insufficiently flat or uneven laying surface can be leveled with cement-based leveling compounds, such as LIVELLANTE 140M, RASODUR MAXI, ULTRADUR, RASODUR, LEVELFAST or LEVELFAST S after priming the surface with PRIMER 99 to promote adhesion. Poorly or completely non-absorbent surfaces must always be smoothed to a minimum thickness of at least 2-3 mm applying ECOGRIP PLUS or ECOGRIP as an adhesion promoter.

Anhydrite substrates should be treated according to the manufacturer's instructions. Non-heating substrates that still have an excessive degree of residual moisture (max. 5%) when the flooring is laid must be sealed with appropriate primers, such as: PU series, EPOPRIMER or TRIX, depending on the absorbency of the surface, sanded and then smoothed with a minimum thickness of at least 2-3 mm. In this case, it is necessary to spread plenty of dry siliceous sand of a suitable grain size (0.5-1 mm) on the last coat of waterproof treatment while it is still fresh, subsequently removing any excess sand not anchored after the primer has dried, to ensure good anchorage of the skim coat to the substrate. Heating substrates can be reinforced but not waterproofed. Equipotential bonding (grounding) must be carried out, following the various methods prescribed by current Standards (CEI, DIN, etc.). The conductive grid made of copper strips (thickness 0.08- 0.1 mm, width 10-25 mm) can be fixed to the substrate using HYCOL KD 4 CONDUTTIVO, spread with a thin toothed trowel (type LECHNER no. 1). Mix the product before use. Apply the adhesive on the substrate using an appropriately sized notched trowel, incorporating any residual surface dust. Wait for the adhesive to partially dry, which should take about 10 minutes, depending on:

the quantity applied, the absorbency of the substrate and the ambient temperature. Then proceed to lay the sheets or tiles on the adhesive, which must still be able to wet the back of the flooring. Apply even pressure over the entire surface of the flooring to ensure full contact with the adhesive, massaging from the center outward to improve adhesion and to remove any air bubbles.

OTHER INFORMATION

Do not use on non-absorbent substrates for the direct gluing of non-breathable materials. A few hours before installation, remove the flooring to be glued from its packaging, laying it on the floor to reduce its tension and allow it to acclimatize to the working environment. The application and gluing times indicated in the product features correspond to an ambient temperature of +20°C and a relative air humidity of 50%. The product should be stored at the same temperature as the desired room.

INSTRUCTIONS

FOR SAFETY AND DISPOSAL: Consult the relevant safety data sheet before using the product. Gloves are recommended during use. Ventilate the room during and after use. Follow all applicable safety regulations. Do not dispose of any residue in the ground, waterways or drains. To dispose of the product and other waste deriving from the activity, adhere closely to the provisions of Legislative Decree no. 152/2006 and subsequent amendments and additions of the Consolidated Environmental Act (Testo Unico Ambientale). For further information, please contact our Technical Assistance Department. The content of this sheet integrates and replaces the previous version, rendering it null and void.

WARNINGS: The data provided in this data sheet reflects our best theoretical and practical knowledge. However, it is not possible for us to consider every detail, therefore this information should not be considered as binding. In the event of any doubt, please contact our technical offices.